

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC037N08NS5	**Issued**	16. July 2019
MA#	MA004038190		
Package	PG-TDSON-8-50	**Weight***	106.95 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.175	1.10	1.10	10988	10988
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		127	
	non noble metal	zinc	7440-66-6	0.055	0.05		510	
	non noble metal	iron	7439-89-6	1.090	1.02		10194	
	non noble metal	copper	7440-50-8	44.271	41.39	42.47	413929	424760
wire	noble metal	gold	7440-57-5	0.042	0.04	0.04	393	393
encapsulation	organic material	carbon black	1333-86-4	0.084	0.08		787	
	plastics	epoxy resin	-	3.870	3.62		36185	
	inorganic material	silicondioxide	60676-86-0	38.112	35.63	39.33	356339	393311
leadfinish	non noble metal	tin	7440-31-5	1.264	1.18	1.18	11816	11816
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	271	271
solder	noble metal	silver	7440-22-4	0.041	0.04		380	
	non noble metal	tin	7440-31-5	0.081	0.08		761	
	non noble metal	lead	7439-92-1	1.505	1.41	1.53	14075	15216
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		43	
	non noble metal	zinc	7440-66-6	0.018	0.02		172	
	non noble metal	iron	7439-89-6	0.368	0.34		3438	
	non noble metal	copper	7440-50-8	14.930	13.96	14.32	139592	143245
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com